

portion includes opposed side rails oriented along a length of the glide head and the at least one thermal transducer is formed along a portion of a length of at least one of the opposed side rails.

5. (Amended) The glide head of claim 4 wherein each of the opposed side rails includes at least one thermal transducer.

6. (Amended) The glide head of claim 2 wherein the at least one thermal transducer is in electrical contact with electrically conductive pads proximate to the trailing edge of the glide body.

7. (Amended) The glide head of claim 6 including conductive strips conductively coupled to the at least one thermal transducer and the conductive pads to provide an electrical contact between the thermal transducer and the pads.

9. (Amended) The glide head of claim 2 wherein the at least one thermal transducer extends along at least half of a length distance between the leading edge and the trailing edge of the glide body.

10. (Amended) The glide head of claim 2 wherein the at least one thermal transducer extends substantially from the leading edge to the trailing edge of the glide body.

11. (Amended) The glide head of claim 2 and comprising a plurality of thermal transducers.

12. (Amended) The glide head of claim 11 wherein a first thermal transducer and a second thermal transducer share a common electrical ground.

13. (Amended) The glide head of claim 11 wherein the plurality of

Sub
9/6/14
amended
F8
F9
F10
F11
F12
F13
F14
F15
F16
F17
F18
F19
F20
F21
F22
F23
F24
F25
F26
F27
F28
F29
F30
F31
F32
F33
F34
F35
F36
F37
F38
F39
F40
F41
F42
F43
F44
F45
F46
F47
F48
F49
F50
F51
F52
F53
F54
F55
F56
F57
F58
F59
F60
F61
F62
F63
F64
F65
F66
F67
F68
F69
F70
F71
F72
F73
F74
F75
F76
F77
F78
F79
F80
F81
F82
F83
F84
F85
F86
F87
F88
F89
F90
F91
F92
F93
F94
F95
F96
F97
F98
F99
F100

thermal transducers are spaced along the elevated bearing surface and the glide head further comprises electrically conductive strips in electrical contact with the plurality of thermal transducers, the strips being formed on a recessed bearing surface offset from the elevated bearing surface.

15. (Amended) The glide head of claim 2 in combination with an asperity detection system.

16. (Thrice Amended) A method of fabricating a glide head comprising:
fabricating an air bearing including a raised bearing surface and a recessed surface; and
depositing a thermal transducer on the raised bearing surface to form a glide interface to detect asperities.

18. (Twice Amended) A method of fabricating a glide head from a wafer comprising;
slicing a plurality of glide heads from the wafer; and
depositing thermal transducers on the plurality of glide heads sliced from the wafer.

21. (Amended) The method of claim 18 and further comprising:
fabricating an air bearing on the plurality of glide heads sliced from the wafer including a raised bearing surface and a recessed bearing surface prior to the deposition of the thermal transducers; and
depositing the thermal transducers on the raised bearing surfaces of the plurality of glide heads sliced from the wafer.

Please add new claims 23-26 as follows:

23. (New) The glide head of claim 2 including a plurality of spaced

Sub F 1200
C 1200
Sub F 1200
C 1200
thermal transducers spaced along a length of the glide head between the leading edge and the trailing edge of the glide body.

24. (New) The glide head of claim 2 including a protective layer deposited on the at least one thermal transducer.

Sub F 1200
C 1200
Sub F 1200
C 1200
25. (New) A glide head comprising:
a glide body including a leading edge, a trailing edge and a raised bearing portion; and
asperity detection means on the glide body for detecting asperities on a disc surface.

26. (New) The method of claim 16 wherein the fabrication of the air bearing and the deposition of the thermal transducer is performed onto a surface of a wafer prior to slicing a plurality of glide heads from the wafer.
